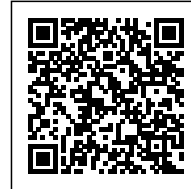


**FEEDING EQUIPMENT
DIE EJECT UNIT WITH SINGLE WAFER CHANGER**

SKU: S3-0097.02

99.000,00 € excl. VAT



Categories: [Feeding equipment](#), [Modules](#)

BESCHREIBUNG

The wafer system consisting of Die Eject Unit and Single Wafer Changer is used to load wafers and to release components from the wafer foil to make them available to the machine for further processing. The components fixed on the wafer foil are released with a Needle Vacuum System and thus separated.

The Wafer Changer is used to feed a wafer to be processed and to remove the processed wafer. An integrated magazine enables to provide automatically up to 25 wafers with a size of 4" to 8" alternately one after the other.

The wafers are fed in without opening the doors of the machine.

The Wafer Changer is equipped with a laser safety window, which allows the wafer system to be used in machines with laser applications.

MORE INFORMATION

Max. wafer size in inch / mm	8 / 200
Voltage in V	24
Max. current in A	5
Communication interface	Ethernet , UNICAN

Häcker Automation GmbH
Inselsbergstraße 17
99880 Waltershausen / OT
Schwarzhausen

 **mikromontage.shop**

Contact us:
Consulting: +49 (0)36259 300 99
Support: +49 (0)36259 300 711
E-Mail: contact@haecker-automation.com

